

**Highly-accelerated temperature and
humidity stress test (HAST)**

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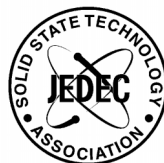
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INTERNATIONAL
ELECTROTECHNICAL
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EIA/JEDEC STANDARD

Test Method A110-B

Highly-Accelerated Temperature and Humidity Stress Test (HAST)

JESD22-A110-B

(Revision of Test Method A110-A)

FEBRUARY 1999

ELECTRONIC INDUSTRIES ALLIANCE

JEDEC Solid State Technology Association



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INTERNATIONAL ELECTROTECHNICAL COMMISSION

HIGHLY-ACCELERATED TEMPERATURE AND HUMIDITY STRESS TEST (HAST)

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IEC-PAS 62177 was submitted by JEDEC and has been processed by IEC technical committee 47: Semiconductor devices.

The text of this PAS is based on the following document:

This PAS was approved for publication by the P-members of the committee concerned as indicated in the following document:

Draft PAS	Report on voting
47/1450/PAS	47/1483/RVD

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